

NMC508M ALUMINUM METAL ETCH SYSTEM

System Overview

The NMC508M is an ICP high-density plasma dry etching tool used for aluminum and tungsten etching of 200 mm wafers predominantly in Power and Logic ICs. It is a fully automated multi-chamber cluster tool capable of serial or parallel processing.

Substrate Size:	200 mm
Applications compounds:	Aluminum, Tungsten
Technology Markets:	Analog IC, Digital IC, Power IC

Processes

- Top/Inter/Bottom metal interconnect etch followed by photoresist strip

Production Advantages

- Planar ICP with automatic matching and magnetic shield generates high plasma uniformity across the wafer
- Independent control of center and edge gas injection optimizes etch rate uniformity
- Process chamber adopts an internal door structure to improve the uniformity of plasma distribution
- Robust end point detection system maximizes signal-to-noise performance
- Excellent defect control capability using proprietary particle control technology
- Photoresist strip module equipped with integrated microwave RF generator design that does not require disassembly during preventive maintenance cleaning



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